

Connector Datasheet

PT06J0000DY8

RJ45 1×1 Tab Up Only Right LED & W/O Spring
W/1000 Base-T Transformer

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TECHNICAL INFORMATION

1 SCOPE

1.1 Content

1.1.1 This specification covers performance, tests and quality requirements for RJ45 1×1 Tab Up Only Right LED & W/O Spring
W/1000 Base-T TransformerW/2.5G Transformer

2 APPLICABLE DOCUMENTS

The following documents form a part of this specification to the extent specified herein.
Unless otherwise specified, latest edition of the specification applies. In the event of conflict between requirements of this specification and product drawing, product drawing shall take precedence.

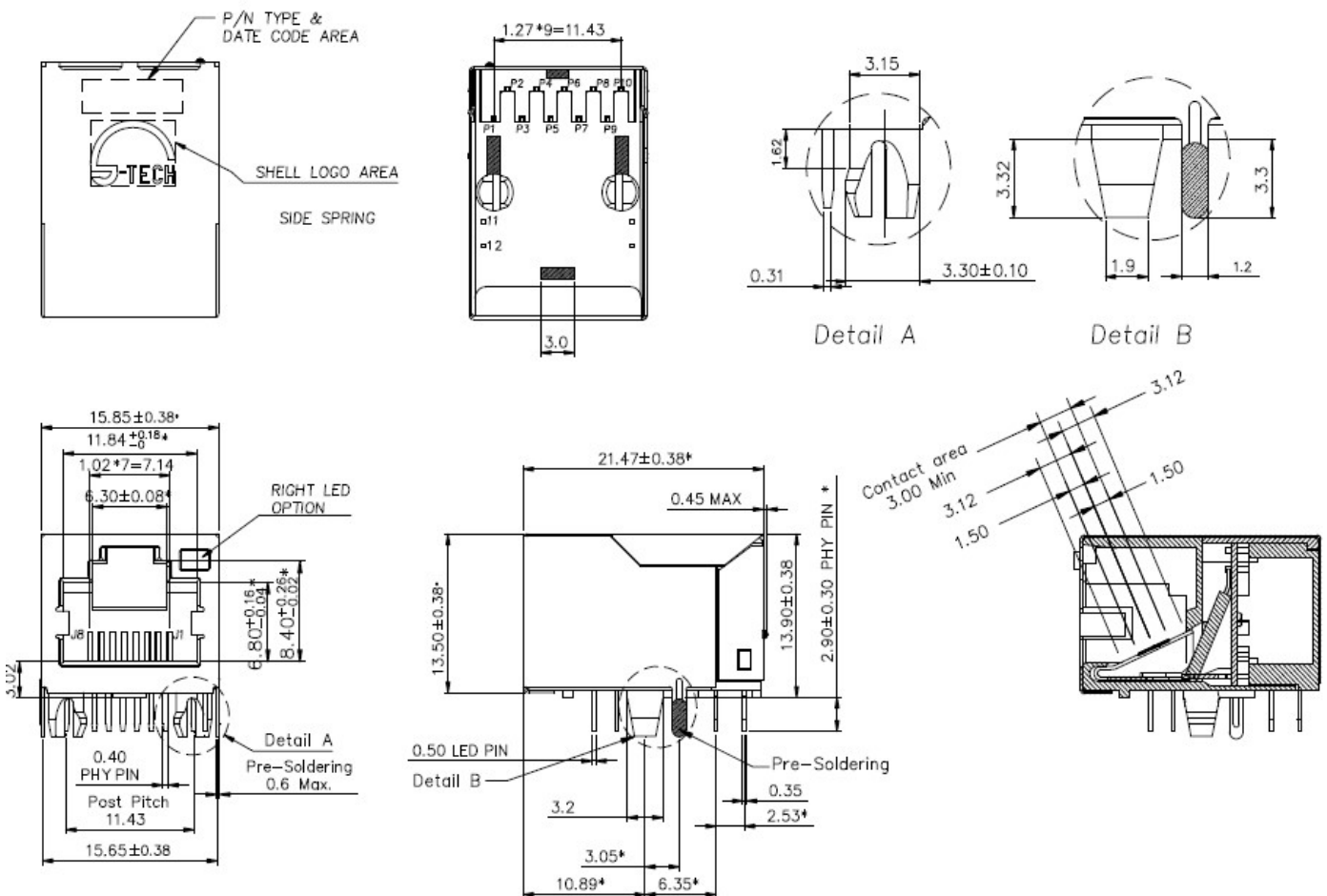
2.1 Commercial standards, specifications and report

2.1.1 MIL-STD-1344A

2.1.2 EIA-364

3 MECHANIC DIMENSIONS

Component Configuration and Dimensions

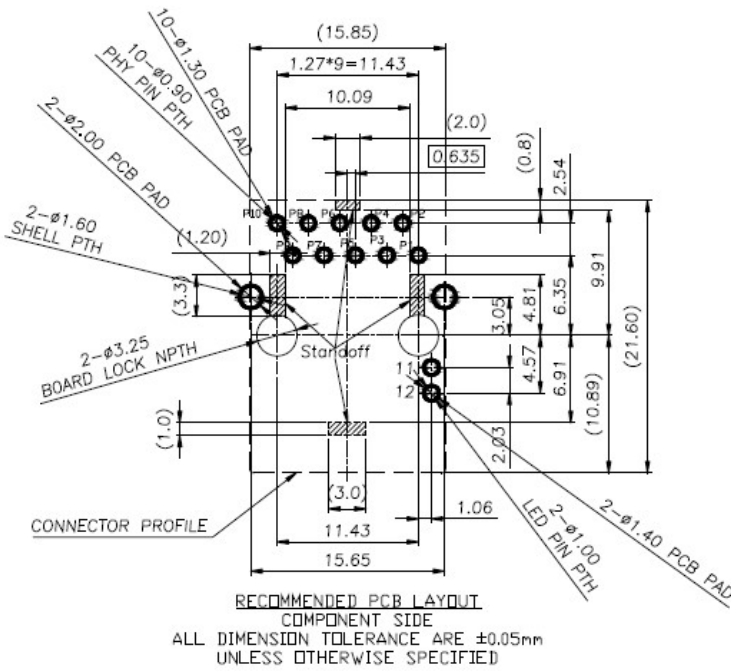


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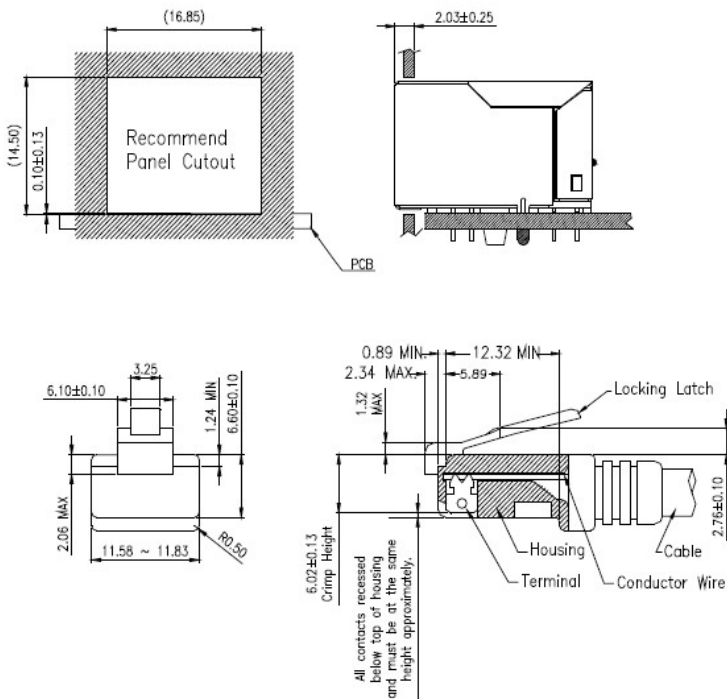
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Pins assignment for PCB Layout



Recommend Panel Cutout and Plug



All dimensions follow :
 FCC subpart F, 68,500, Figure (C)(2)(i)
 IEC 60603-7

STANDARD MODULAR PLUG ASSEMBLY

4 REQUIREMENTS

4.1 Design and Construction

4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.

4.2 Materials and Finish

4.2.1 Contact:

4.2.1.1 RJ Contact: Phosphor bronze

Finish: (a) Contact Area : 0.75 μ m Au Min

(b) Solder tail Area : 100u” Min Matted Tin

(c) Under plating : 50 u” Min Nickel over all

4.2.1.2 Joint Contact: Brass

Finish: (a) 100 u” Min Matted Tin over all

(b) Under plating: 50-100 u” Nickel over all

4.2.2.1 Housing: High temperature engineering Plastic, PA46, Yellow(114C)

Flame Class: UL94 V-0

4.2.2.2 Insert: High temperature engineering Plastic, LCP, Black

Flame Class: UL94 V-0

4.2.2.3 Cover: High temperature engineering Plastic, PA46, Black

Flame Class: UL94 V-0

4.2.2.4 Module: High temperature engineering Plastic, PA46, Black

Flame Class: UL94 V-0

4.2.3 Shell

4.2.3.1 Shell: Stainless steel

4.2.3.2 Shell of Grounding Pin : pre-soldering Sn

4.2.4 LED Lamp

Emitting color	λ_p (nm)	$V_f@I_f=20mA$	$I_r@V_r=5V$
Green	562-568 typ565	1.7-2.6typ 2.2	10uA max

4.3 Operating and Storage Temperature

4.3.1 Operating Temperature : 0°C TO +70°C

4.3.2 Storage Temperature : -40°C TO +85°C

4.4 Mechanical Characteristics

4.4.1 Mating force : 20N MAX

4.4.2 Unmating force(w/o tab locking): 20N MAX

4.4.3 Durability : 1000 cycles

4.5 Reliability Test:

4.5.1 Resistance to soldering heat - High Temperature Resistance:

265+5/-0°C , 3-5 seconds for 2 times.

4.5.2 Rework temperature: 350°C Max. 3~5seconds for 3 times.

4.6 Environmental Test:

4.6.1 Moisture Resistance : MSL level-1

4.6.2 Saving life: 1 year

4.6.3 Thermal shock cycle Test: Expose Sample connectors under the temperature changes between -40°C and 85°C for 25 cycles holding for 30minutes at the both extremes, in accordance with test method of SPEC.

4.6.4 Temperature life: Subject Sample connectors to temperature of 85°C for 168 hours. It shall be subjected to standard atmospheric.

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Class shall be satisfied. MIL-STD-1344A.method:1002.2.

4.7 Performance and Test Description

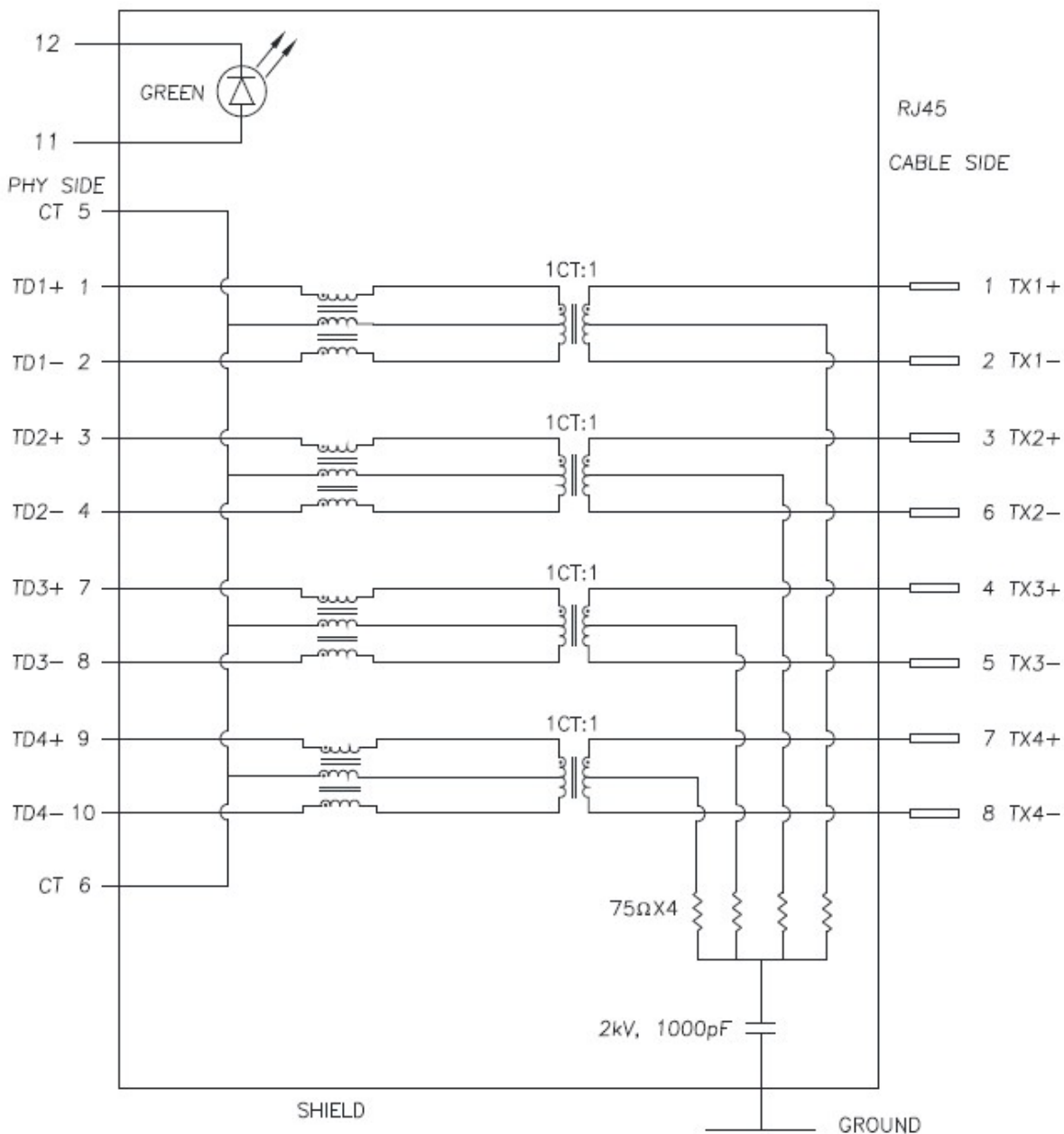
Product is designed to meet electrical, mechanical and environmental performance requirements. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

4.8 Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.

5 ELECTRICAL CHARACTERISTICS

5.1 Schematic



5.2 Insertion loss :

1-100 MHz - 1.0dB MAX.

100~125 MHz - 1.2dB MAX.

Return loss : 1-30 MHz - 18dB MIN. load 100 OHM

30-60 MHz - 16dB MIN. load 100 OHM

60-80 MHz - 12dB MIN. load 100 OHM

80-100 MHz - 10dB MIN. load 100 OHM

5.3 Common Mode Rejection

@ 1-100 MHz - 30dB MIN.

5.4 Cross Talk

@ 1-100 MHz - 30dB MIN.

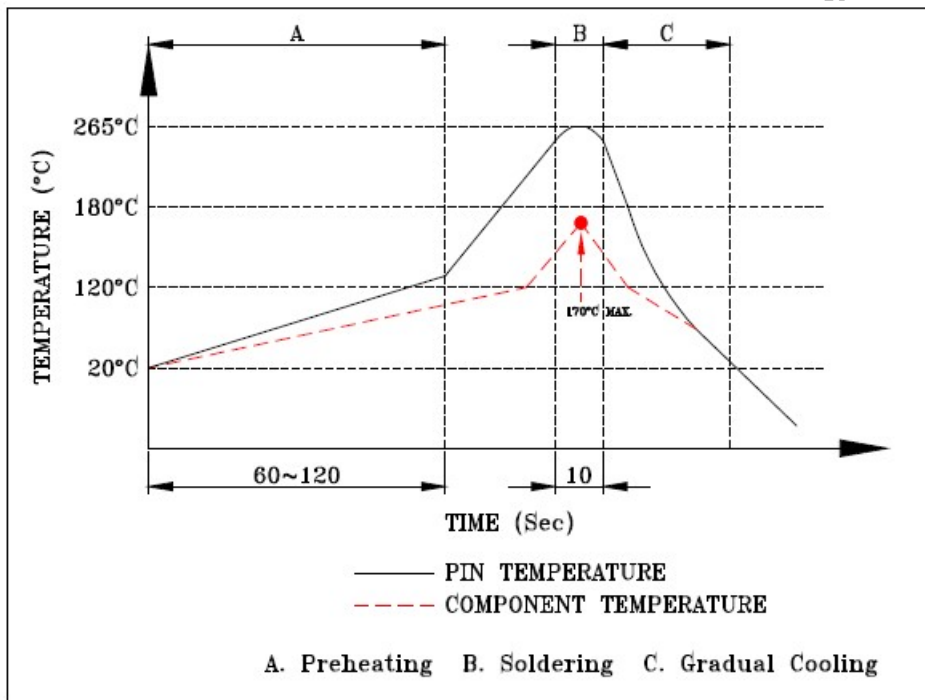
5.5 Primary Inductance@ 100KHz, 0.1V, 8mA DC BIAS

P(1-2), P(3-4), P(7-8), P(9-10): 350uH MIN.

5.6 Hi-Pot TEST

PRIMARY TO SECONDARY: 2250 VDC.

Resistance to flow solder heat



SUGGESTED WAVE SOLDER CURVE

(1)Tip temperature : 265+5/-0°C

(2)Tip temperature time : 3~5sec

Note: The product specification only for standard product